

THE 11th INTERNATIONAL WORKSHOP ON THE ELECTROMAGNETIC COMPATIBILITY OF INTEGRATED CIRCUITS

RUSSIA, Saint Petersburg

Saint Petersburg Electrotechnical University «LETI»



**4-8
July, 2017**

Celebrating 120th anniversary of the world first radiogram being sent

CALL FOR PAPERS

The achievements in terms of operating frequency and integration of semiconductor technology are constantly creating new challenges in EMC, which must be addressed at both the integrated circuit and system level. Keeping up-to-date is of paramount importance to be successful in this field. EMC Compo 2017 is a place for exchange of the latest research achievements and experience in IC-level EMC and it is addressed to researchers and engineers both from industry and from academia. The workshop is focused on emission and susceptibility issues in digital, analogue and mixed-signal integrated circuits. The most recent advances in simulation and measurement techniques, models, standards, tools and design methodologies will be discussed. A Technical Exhibition will provide tool and equipment manufacturers and suppliers an opportunity to display their products and services to potential clients.

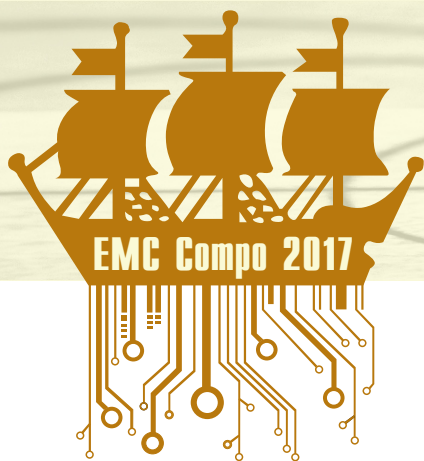
EMC Compo 2017 also coincides with the 120th Anniversary of the world first radiogram being sent. Alexander Popov, the inventor of radio, was the first elected principal of the Saint Petersburg Electrotechnical University «LETI». There will be an opportunity to visit his memorial laboratory, where he carried out his researches in the field of radio signal transmission.

SCOPE AND TOPICS

- Measurement and modeling of IC emissions and susceptibility
- Signal Integrity and Power Integrity at IC and PCB level
- EMC-aware IC Design and Guidelines
- Tools to handle EMC at IC level
- Computational Electromagnetics for IC level EMC
- EMC issues in System-on-chip (SoC), System-in-Package (SiP), and 3D ICs
- EMC issues in smart power ICs
- EMC of ICs in wireless communications
- EMC of ICs for biomedical applications
- Materials for improved EMC of ICs
- Harsh environment effects on IC level EMC
- Long term electromagnetic robustness of ICs
- Standards and regulations up to 6 GHz
- Modern EMC education on IC level EMC
- Influence of IC EMC on system design
- Intentional Electromagnetic Interference

Contact Us: IRVC.eltech@mail.ru

WWW.EMCCompo2017.eltech.ru



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INFORMATION FOR AUTHORS AND EXHIBITORS

Deadline for paper submission: **Mon 23d Jan. 2017**

Tutorial proposals: **Mon 20th Feb. 2017**

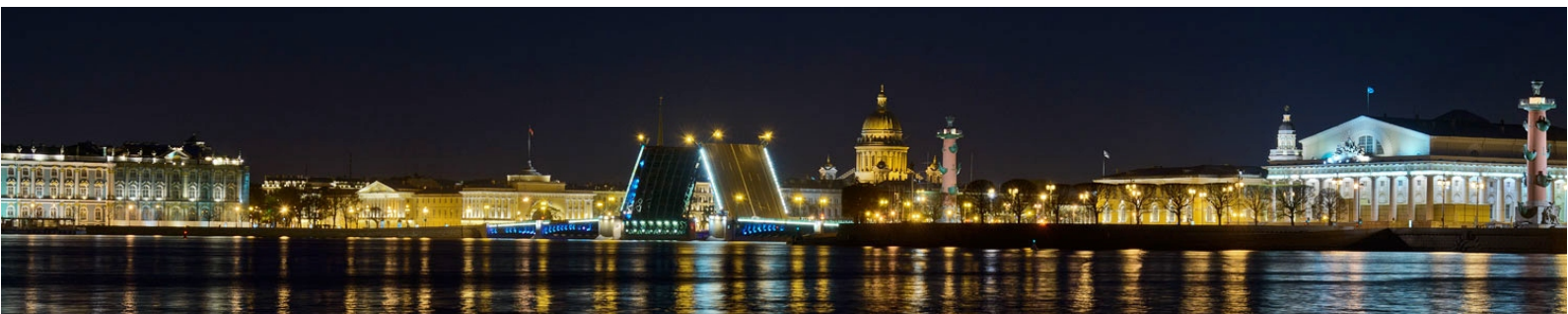
Notification of acceptance: **Mon 20th Feb. 2017**

Final paper submission: **Tue 23th May 2017**

Instructions for authors and exhibitors can be found on the conference web site. Enquiries: IRVC.eltech@mail.ru

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